

**IMAGINE  
THE IMPACT™**

# Power Electronics: Simulation Solutions

**BOSTON  
ENGINEERING™**  
Imagine the Impact™

**Ansys**

# Significant Challenges Exist To Deliver Power Electronics Technology

• Performance

• Safety

• Cost



Switching frequencies

> 20 kHz



Over-voltages

< Dielectric breakdown



Thermal reliability

< Thermal limits



System optimization

Product requirements



EMI/EMC

Meeting standards



Life

> 10 years

# Multidisciplinary Power Electronics Design Requirements

**Goal:** An integrated, efficient multidisciplinary design workflow to increase power density and lifetime, while reducing losses, thermal derating, noise and over-voltages

Increased Collaboration; Faster Innovation; Customized Workflows; Optimization; Cloud & HPC

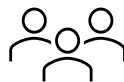
## Electrical Team



**System &  
Circuit  
Design**

Optimize system and circuit to increase efficiency

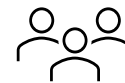
## Mechanical Team



**Reliability**

Enhance PCB reliability to mitigate component failure

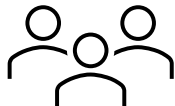
## Software Team



**Embedded  
Controls**

Safe embedded controls to detect flaws in requirements, design and tests

## Electromagnetic and Thermal Team



**Magnetic  
Analysis**

Account for magnetics to increase power density

**Thermal  
Management**

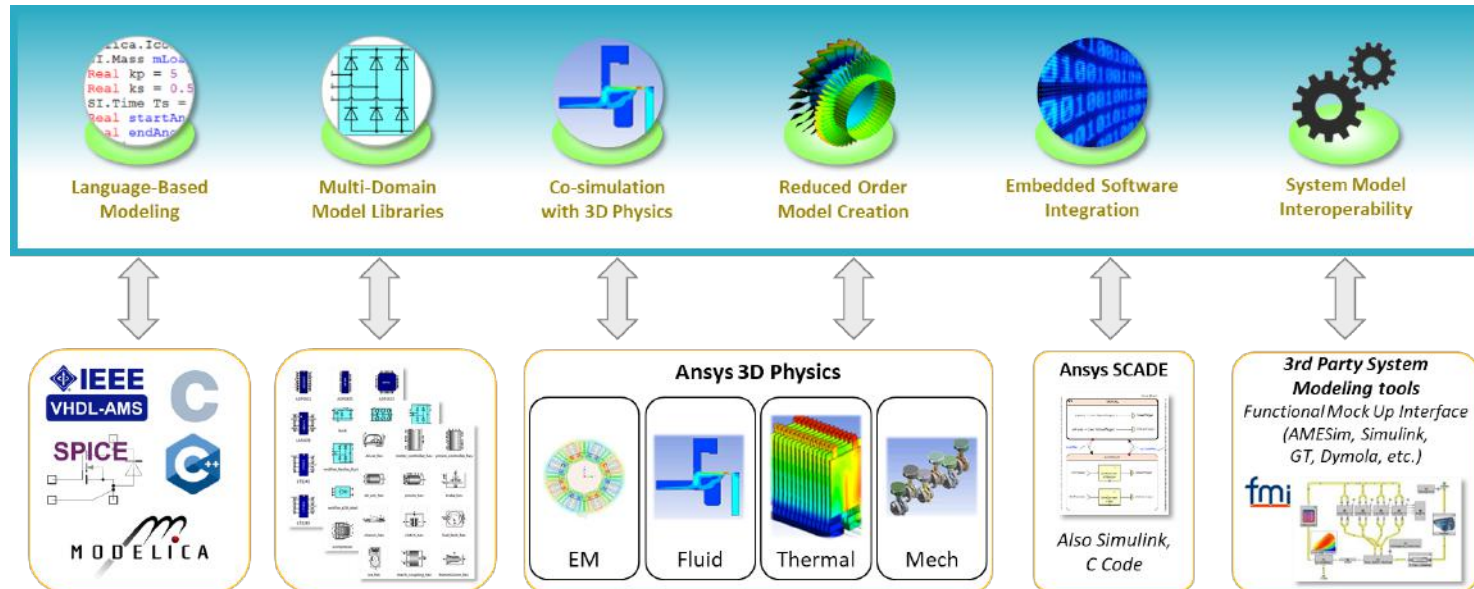
Enhance thermal performance to mitigate component failure

**EMI/EMC**

Master EMC certification to meet standards

# Optimize System and Circuit Design

## Multidomain circuit and system simulation



### Customer Goal

- Enable **higher power densities** in smaller footprint
- **Increase efficiency** with higher switching frequencies
- Overcome **EMI/EMC** and **thermal issues**

### Solution

- **Multidomain circuit and system simulation**
- Complex **system models, model libraries** and **reduced-order model workflows**
- Power device characterization at **different levels of accuracy** depending on need

### Benefits

- **Enable** broader application range
- **Reduced** test cycle for EMI/EMC
- **Reduced** failures due to thermal stress
- **Increased** competitive advantage



# Enhanced PCB Reliability

## Customer Goal

- Mitigate **failure of electronic components**
- Meet **standard test criteria** with reduced physical prototyping

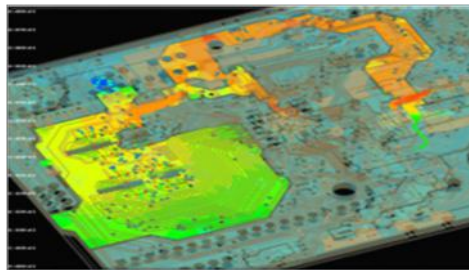
## Solution

- **Lifetime prediction**
- Coupled physics simulations in a **single platform**
- Electronics **CAD** formats import capability,
- **Easy to use**
- **Broad material and component library**

## Benefits

- **Reduce costs** associated with physical testing through virtual exploration and validation
- **Rapidly calculated PCB-Level Time-to-Failure** estimates for all components on a board

Import of **electronics CAD** formats



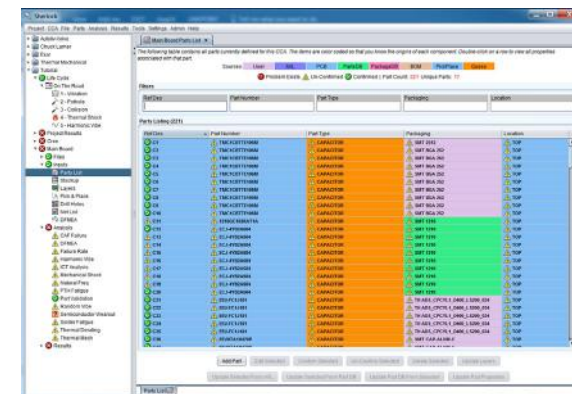
Coupled physics simulations in a **single platform**



**Lifetime prediction**



**Material and component library**



# Safe Embedded Controls

## Customer Goal

- **Virtual prototyping of hardware and software** prior to physical integration and testing
- Enable **early validation** to detect flaws in requirements, design and tests

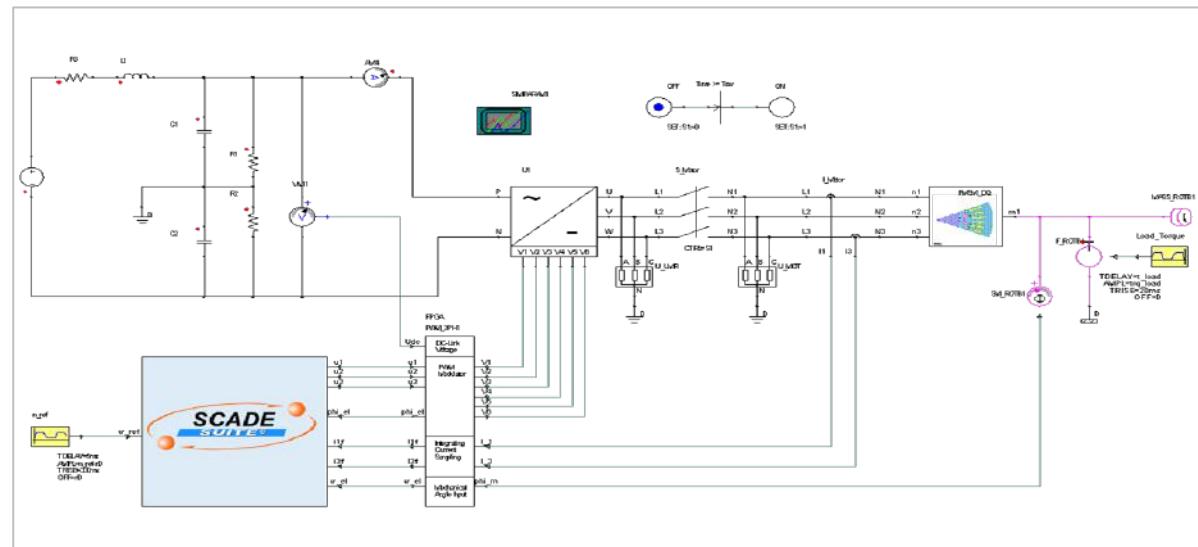
## Solution

- **Flexible platform** for embedded software integration with physics-based reduced-order models and **extensive library**
- **Qualified code generation**
- System level models with ability to export and consume **FMI/FMU**
- **Flexible and scalable** Model Based System Engineering approach

## Benefits

- **Reduced development time and cost** through seamless certification flow and early verification and validation
- **Ensured safety** of embedded software

## Flexible platform with system level models and FMI interface



# Account for Magnetics

## Customer Goal

- Don't exceed temperature limits for inductors and transformers
- Reduced size/ footprint
- Avoid leakage inductance, over voltages and parasitic effects

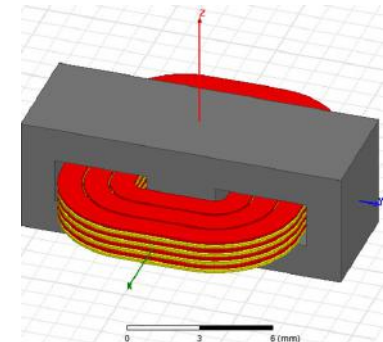
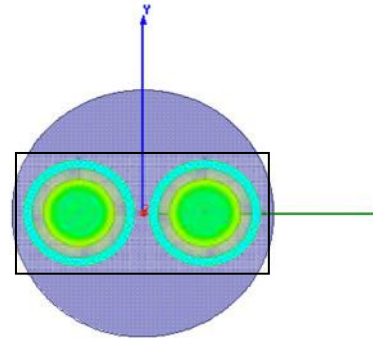
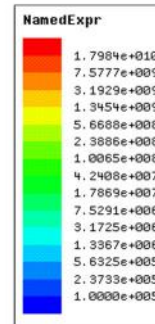
## Solution

- Models for power magnetic components and electric machines
- Skin and proximity effects consideration
- Component model coupling through co-simulation or reduced-order modelling
- Cover frequency dependent parasitics

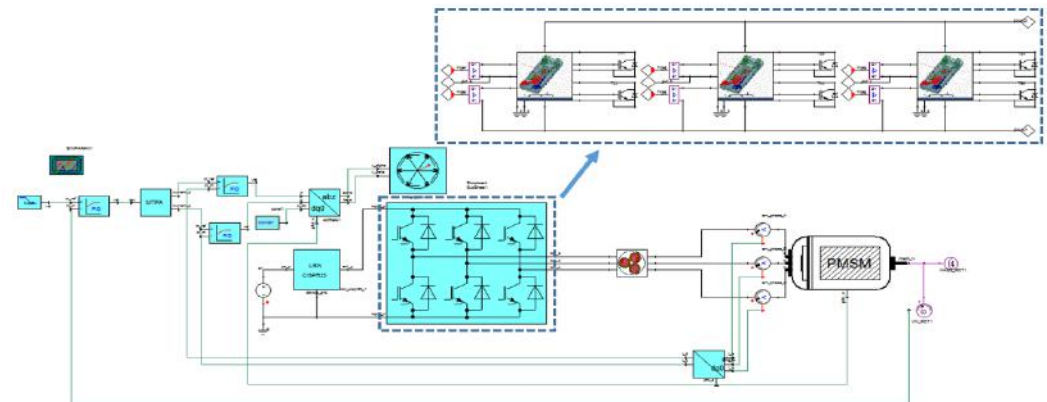
## Benefits

- Increased power density
- Reduced hot spots, operation below thermal limits

Power magnetic components:  
Cable Electronics transformer



## Reduced-order modelling to account for component interaction



# Enhanced Thermal Performance

## Customer Goal

- **Don't exceed temperature limits** for power semiconductors and enclosures
- Prevent **component failure**

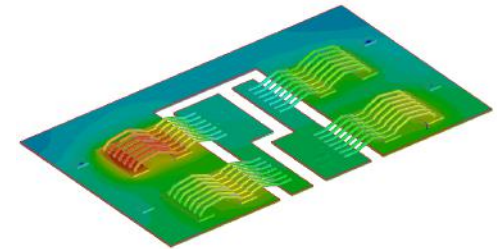
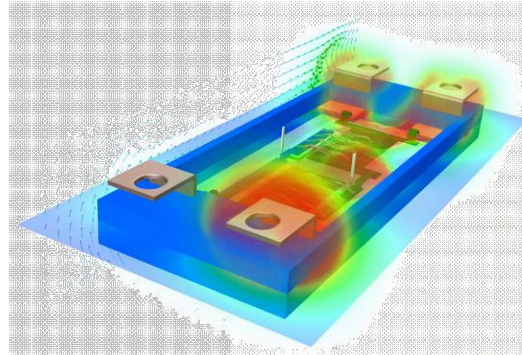
## Solution

- **System thermal performance** analysis with electro-thermal power semiconductor and magnetic models
- **Hot spots and thermal limits prediction** for bus bars and cables
- **Winding and core losses prediction** for magnetic components

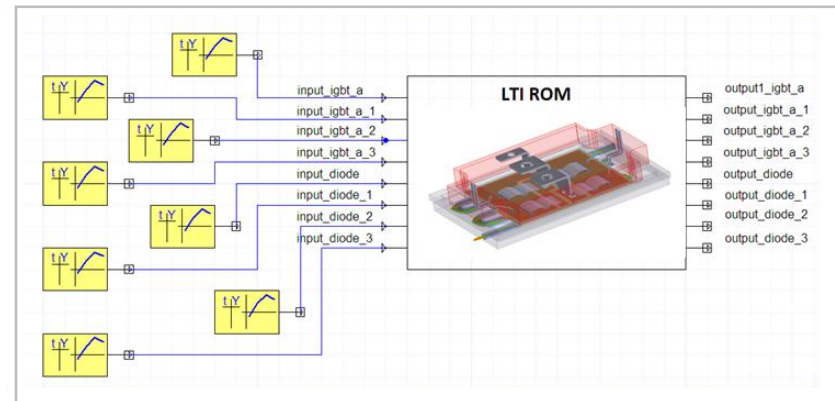
## Benefits

- **Enhanced reliability**
- **Cost-effective** thermal drive-cycle testing
- **Reduced** thermal testing

## Hot spots and thermal limits prediction



## System thermal performance analysis





# Master EMC Certification

## Customer Goal

- Meet required EMC standards
- Reduced number of re-design cycles due to failed EMC tests

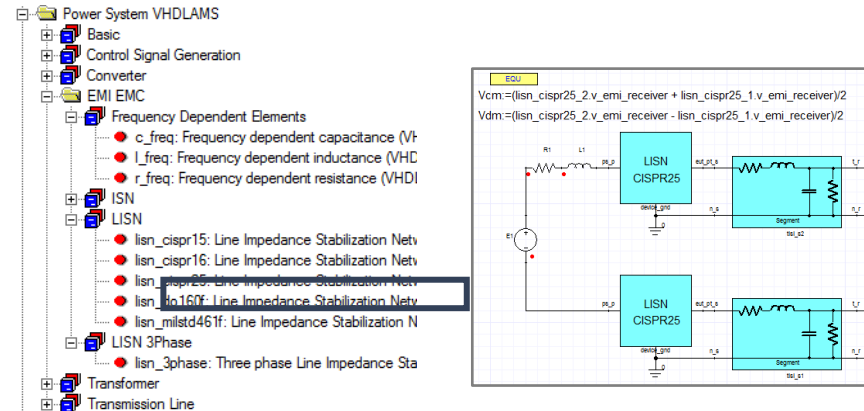
## Solution

- Accurate prediction of power semiconductor switching behavior
- Frequency dependent parasitics prediction
- EMI/EMC components library
- Automated and streamlined workflows
- Radiated and conducted noise prediction

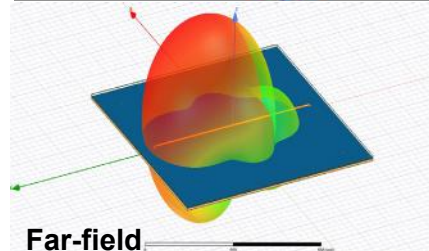
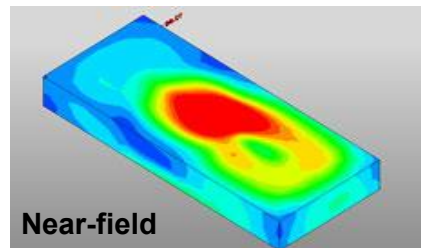
## Benefits

- Early detection and mitigation of EMI/EMC effects
- Weak point localization that cannot be determined by measurements
- Reduced time and costs for tests by 20-40%

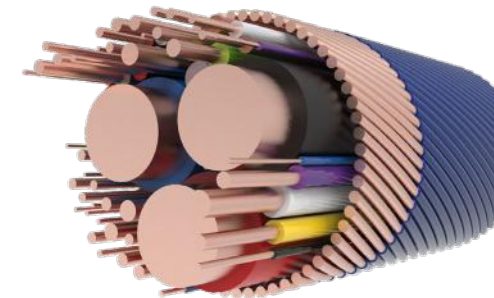
## Conducted EMI/ EMC library



## Radiated noise prediction:



## Automated, streamlined workflows for cable analysis



# Quantified Impact Of Simulation On Power Electronics

Performance

**2000x**

Speed-up using  
reduced-order models<sup>1</sup>

Design Cycle Time  
Reduction

**75%**

Compressed PCB  
development time<sup>2</sup>

Cost  
Reduction

**30%**

Productivity gains<sup>3</sup>

1. <https://www.ansys.com/resource-center/article/hot-flash-ansys-advantage-v10-i1>

2. <https://www.ansys.com/en-in/resource-center/article/driving-down-time-to-market>

3. <https://www.ansys.com/en-in/resource-center/article/leading-the-electric-vehicle-charge>